

# ES1AF **THRU** ES1JF

### SURFACE MOUNT GLASS PASSIVATED SUPER FAST SILICON RECTIFIER VOLTAGE RANGE 50 to 600 Volts CURRENT 1.0 Ampere

#### **FEATURES**

- \* Glass passivated device
- \* Ideal for surface mounted applications
- \* Low leakage current
- \* Metallurgically bonded construction
- \* Mounting position: Any
- \* Weight: 0.027 gram

#### **MECHANICAL DATA**

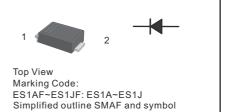
\* Epoxy : Device has UL flammability classification 94V-0

#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified. Resistive or inductive load.

#### **PINNING**

PIN	DESCRIPTION
1	Cathode
2	Anode



# $\textbf{MAXIMUM RATINGS} \ (@\ \textit{TA=25}\ ^{\circ}\textit{C}\ \textit{unless otherwise noted})$

RATINGS	SYMBOL	ES1AF	ES1BF	ES1CF	ES1DF	ES1EF	ES1GF	ES1JF	UNITS
Maximum Recurrent Peak Reverse Voltage	V <sub>RRM</sub>	50	100	150	200	300	400	600	Volts
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	105	140	210	280	420	Volts
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	150	200	300	400	600	Volts
Maximum Average Forward Rectified Current at $T_L = 100^{\circ}\text{C}$	Io	1.0					Amps		
Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	I <sub>FSM</sub>	30					Amps		
Typical Current Square Time	I <sup>2</sup> T	3.7					A <sup>2</sup> S		
Typical Thermal Resistance	R <sub>0JA</sub>	100							°C/W
Typical Thermal Resistance	$R_{\theta JL}$	60							] 0,,,,
Typical Junction Capacitance (Note 2)	CJ	10					pF		
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to + 150				°C			

#### $\textbf{ELECTRICAL CHARACTERISTICS} (@\text{TA=25} \ ^{\circ}\text{C unless otherwise noted})$

CHARACTERISTICS	SYMBOL	ES1AF	ES1BF	ES1CF	ES1DF	ES1EF	ES1GF	ES1JF	UNITS	
Maximum Instantaneous Forward Voltage at 1.0A DC	V <sub>F</sub>	1.0 1.25 1				1.7	Volts			
Maximum DC Reverse Current	@T <sub>A</sub> = 25°C	le.	5.0							
at Rated DC Blocking Voltage	@T <sub>A</sub> = 125°C	lR IR	100							μAmps
Maximum Reverse Recovery Time (Note 1)	trr	35							nSec	

NOTES : 1. Reverse Recovery Test Conditions: IF = 0.5A, IR = -1.0A, IRR = -0.25A

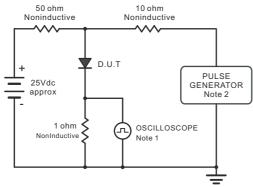
2. Measured at 1 MHz and applied reverse voltage of 4.0 volts

3. Thermal Resistance: Mounted on PCB.

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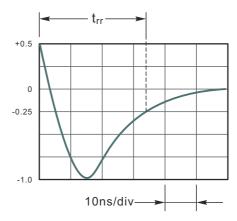
## RATING AND CHARACTERISTICS CURVES (ES1AF THRU ES1JF)

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max. Input Impedance = 1megohm,22pF.

> 2. Ries Time =10ns, max. Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

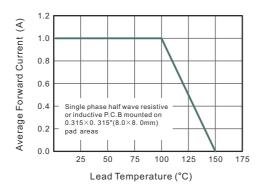


Fig.3 Typical Reverse Characteristics

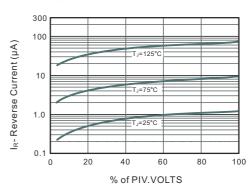


Fig.4 Typical Forward Characteristics

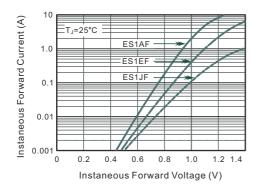
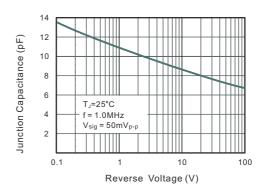


Fig.5 Typical Junction Capacitance

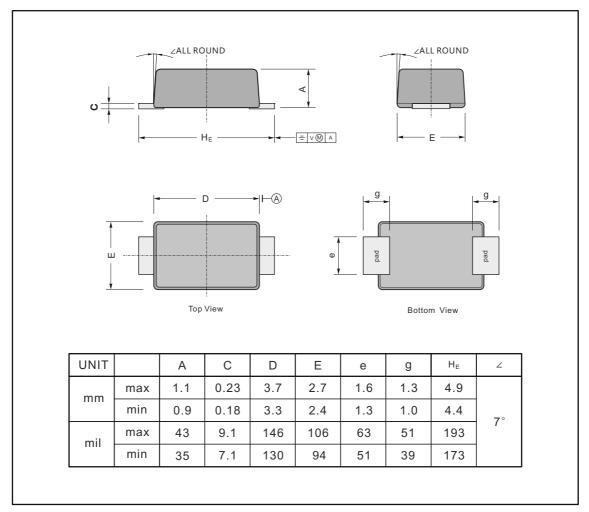




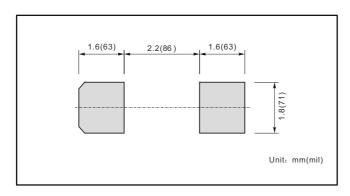
## PACKAGE OUTLINE

## Plastic surface mounted package; 2 leads

### **SMAF**



## The recommended mounting pad size



### Marking

Type number	Marking code					
ES1AF	ES1A					
ES1BF	ES1B					
ES1CF	ES1C					
ES1DF	ES1D					
ES1EF	ES1E					
ES1GF	ES1G					
ES1JF	ES1J					



# PACKAGING OF DIODE AND BRIDGE RECTIFIERS

### REEL PACK

PACKAGE	PACKING CODE	EA PER REEL	EA PER INNER BOX	COMPONENT SPACE (mm)	TAPE SPACE (mm)	REEL DIA (mm)	CARTON SIZE (mm)	EA PER CARTON	GROSS WEIGHT(Kg)
SMAF	-T	3,000	12,000			178	390*205*310	96,000	
SMAF	-W	10,000	20,000			330	360*355*360	160,000	



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